20th Anniversary of KSDT

KISM 2022

Korean International Semiconductor Conference on Manufacturing Technology 2022

November 13-16, 2022 | Paradise Hotel Busan (Haeundae Beach), Busan, Korea

Session Title:	[TB1] Advanced CMP Process & CMP Slurry
Session Date:	November 15 (Tue.), 2022
Session Time:	09:30-11:00
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Sangwoo Lim (Yonsei Univ., Korea)

[TB1-1] 09:30-09:50

Effect of Controlling Slurry Temperature for Chemical Mechanical Planarization

Wenxing xue, Sanghuck Jeon, and Taesung Kim (Sungkyunkwan Univ., Korea)

[TB1-2] 09:50-10:10

Dishing-Free Cu-Film Chemical-Mechanical-Planarization Slurry via Fenton Reaction between Ferrous Catalyst and Hydrogen Peroxide and Accelerating Polishing Rate Using Zwitterion Scavenger

Jae-Young Bae, Sang-Su Yun, Young-Hye Son, Gi-Ppeum Jeong, Je-Hwan Lee, Jong-Han Jeong, Sung-In Kim (Hanyang Univ., Korea), Jin-Hyung Park (UB Materials Inc., Korea), and Jea-Gun Park (Hanyang Univ., Korea)

[TB1-3] 10:10-10:30

Research Trends for Sustainable Chemical Mechanical Polishing

Hyunseop Lee (Dong-A Univ., Korea), Hyoungjae Kim (KITECH, Korea), and Haedo Jeong (Pusan Nat'l Univ., Korea)

[TB1-4] [Invited] 10:30-11:00

Challenges in Chemical Mechanical Planarization for Advanced Memory Devices

Hyo-Chol Koo, Kwoonhwi Seo, Hyun Min Lee, and Byoungki Lee (SK hynix, Korea)